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(54) SEMICONDUCTOR DEVICE

(57) Abstract:

PURPOSE: To reduce inductance, and to prevent the malfunction of a semiconductor device being generated by inductance by directly connecting a capacitor to outer leads for a power supply and a GND in the semiconductor device.

CONSTITUTION: A semiconductor chip 1 with pads 4A, 4B for a GND and a power supply is fixed onto a package 2, to which outer leads 3 including outer leads 3A, 3B for the GND and the power supply are formed and which consists of ceramics, etc. The pads 4A, 4B for the GND and the power supply are connected respectively to the outer leads 3A, 3B for the GND and the power supply by bonding wires 6A, 6B. A capacitor 5 is fastened onto the the outer leads 3A, 3B, and a terminal 7A for the GND and a terminal 7B for the power supply for the capacitor 5 are directly connected respectively to the outer lead 3A for the GND and the outer lead 3B for the power supply. Accordingly, inductance is lowered, noises are reduced, and the generation of a malfunction can be prevented.